11046 U.S. PTO
10/005633
2/05/01

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PATENT NUMBER and ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM	FILING DATE	CLASS	SUBCLASS	GAU	EXAMINER
10005633	12/05/2001	257 ~~926~~	735	2827 ~~3729~~	[illegible]

**APPLICANTS: Slemmons John; Messner Jay; Woolston Frank; Redmond Patrick; Zappella Pierino; Fewer William;

**CONTINUING DATA VERIFIED:

THIS APPLICATION IS A DIV OF 09/383,720 08/26/1999

** FOREIGN APPLICATIONS VERIFIED:

REPUBLIC OF KOREA 68665/2000 11/18/2000

PG-PUB DO NOT PUBLISH ☐ RESCIND ☐

Foreign priority claimed ☐ yes ☐ no

35 USC 119 conditions met ☐ yes ☐ no

Verified and Acknowledged Examiners's Intials

ATTORNEY DOCKET NO

A11-26124 D1

TITLE : Microbeam assembly for integrated circuit interconnection to substrates

U.S. DEPT. OF COMM./PAT.& TM-PTO-436L(Rev. 12-94)

NOTICE OF ALLOWANCE MAILED

Assistant Examiner

CLAIMS ALLOWED

Total Claims	Print Claim for O.G
	7

ISSUE FEE

Amount Due	Date Paid

DRAWING

Sheets Drwg.	Figs.Drwg.	Print Fig.

Primary Examiner

☐ **TERMINAL DISCLAMER**

PREPARED FOR ISSUE

Application Examiner

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